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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Mostafazadeh et al.

Attorney Docket No.:
NSC1P226R/P03856R1

Application No.: 10/016,750

Examiner: Unassigned

Filed: December 10, 2001

Group: Unassigned

Title: LEAD FRAME DESIGN FOR
INCREASED CHIP PINOUT

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on January 31, 2005 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: _____


Lara M. Nelson

REQUEST FOR STATUS


Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant hereby requests status of the above-referenced patent application. This application was filed on December 10, 2001 and no response has been received as of this date.

Respectfully submitted,

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